

SCOPE: QUAD, SPDT, CMOS ANALOG SWITCH

| | | |
|--------------------|-----------------------|-------------------|
| Device Type | Generic Number | SMD Number |
| 01 | MAX333M(x)/883B | 5962-93180 |

Case Outline(s). The case outlines shall be designated in Mil-Std-1835 and as follows:

| Outline Letter | Mil-Std-1835 | Case Outline | Package Code |
|-----------------------|------------------------|---------------------|---------------------|
| SMD Maxim R JP | GDIP1-T20 or CDIP2-T20 | 20 LEAD CERDIP | J20 |

Absolute Maximum Ratings

Voltage Referenced to V⁻

| | |
|---|----------------------------------|
| V ⁺ to V ⁻ | 44V |
| V ⁺ to GND | 44V |
| V ⁻ to GND | -44V |
| V _{IN} , V _{COM} , V _{NO} , V _{NC} | V ⁺ to V ⁻ |
| V _{NO} to V _{NC} | 32V |
| Current, Any terminal except V _{COM} , V _{NO} , or V _{NC} | 30mA |
| Current, V _{COM} , V _{NO} , or V _{NC} | 20mA |
| Peak Current, V _{COM} , V _{NO} , or V _{NC} (Pulsed at 1ms, 10% duty cycle max) | 70mA |
| Lead Temperature (soldering, 10 seconds) | +300°C |
| Storage Temperature | -65°C to +150°C |
| Continuous Power Dissipation 1/ | T _A =+70°C |
| 20 lead CERDIP(derate 11.1mW/°C above +70°C) | 889mW |
| Junction Temperature T _J | +150°C |
| Thermal Resistance, Junction to Case, ΘJC: | |
| Case Outline 20 lead CERDIP..... | 40°C/W |
| Thermal Resistance, Junction to Ambient, ΘJA: | |
| Case Outline 20 lead CERDIP..... | 90°C/W |

Recommended Operating Conditions

| | |
|---|-----------------|
| Ambient Operating Range (T _A) | -55°C to +125°C |
| Positive Supply Voltage (V ⁺) | +15V |
| Negative Supply Voltage (V) | -15V |
| V _{INL} (max) | 0.8V |
| V _{INH} (min) | 2.4V |

1/ Device mounted with all leads soldered to PC board.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TABLE 1. ELECTRICAL TESTS

| TEST | Symbol | CONDITIONS -55 °C <=T _A <= +125°C V ⁺ =+15V, V ⁻ =-15V, GND=0V V _{INH} =2.4V, V _{INL} =0.8V Unless otherwise specified | Group A Subgroup | Device type | Limits Min <u>2/</u> | Limits Max <u>2/</u> | Units |
|-----------------------------------|---------------------|---|---------------------|----------------|----------------------------|----------------------------|-------|
| SWITCH | | | | | | | |
| Analog-Signal Range | V _{ANALOG} | | 1,2,3 | All | -15 | 15 | V |
| Drain-Source ON Resistance | r _{DS(ON)} | I _{COM} =1mA, V _{ANA} =±10V, | 1 2,3 | All | | 175 250 | Ω |
| ON Leakage Current | I _{L(ON)} | V _{ANA} =±14V, V _{OFF} =±14V | 1 2 | All | -5 -200 | 5 200 | nA |
| OFF Leakage Current | I _{L(OFF)} | V _{ANA} =±14V, V _{OFF} =±14V | 1 2 | All | -5 -100 | 5 100 | nA |
| INPUT | | | | | | | |
| Input Current | I _{IN} | | 1,2,3 | All | -10 | 10 | μA |
| SUPPLY | | | | | | | |
| Positive Supply Current | I ₊ | All channels on or off | 1 2,3 | All | -.25 .50 | .25 .50 | mA |
| Negative Supply Current | I ₋ | All channels on or off | 1 2,3 | All | -.25 .50 | .25 .50 | mA |
| DYNAMIC | | | | | | | |
| Turn-On Time | t _{ON} | | 9 10,11 | All | | 500 1000 | ns |
| Turn-Off Time | t _{OFF} | | 9 10,11 | All | | 1000 2000 | ns |
| Break-Before-Make Delay <u>3/</u> | t _{OPEN} | | 9 10,11 | All | 50 5 | | ns |

NOTE 2: The algebraic convention whereby the most negative value is a minimum and the most positive value is a maximum, is used in this table. Negative current shall be defined as conventional current flow out of a device terminal.

NOTE 3: Guaranteed, but not tested.

| ORDERING INFORMATION: | SMD Number |
|------------------------------|-------------------|
| MAX333MJP/883B 20 CDIP | 5962-9318001MRA |
| | |

TERMINAL CONNECTIONS:

| | |
|----|----------------|
| | MAX333MJP/883B |
| | J20 |
| 1 | IN1 |
| 2 | NO1 |
| 3 | COM1 |
| 4 | NC1 |
| 5 | V- |
| 6 | GND |
| 7 | NC2 |
| 8 | COM2 |
| 9 | NO2 |
| 10 | IN2 |
| 11 | IN3 |
| 12 | NO3 |
| 13 | COM3 |
| 14 | NC3 |
| 15 | NC |
| 16 | V+ |
| 17 | NC4 |
| 18 | COM4 |
| 19 | NO4 |
| 20 | IN4 |

QUALITY ASSURANCE

Sampling and inspection procedures shall be in accordance with MIL-Prf-38535, Appendix A as specified in Mil-Std-883.

Screening shall be in accordance with Method 5004 of Mil-Std-883. Burn-in test Method 1015:

1. Test Condition, A, B, C, or D.
2. TA = +125°C minimum.
3. Interim and final electrical test requirements shall be specified in Table 2.

Quality conformance inspection shall be in accordance with Method 5005 of Mil-Std-883, including Groups A, B, C, and D inspection.

Group A inspection:

1. Tests as specified in Table 2.
2. Selected subgroups in Table 1, Method 5005 of Mil-Std-883 shall be omitted.

Group C and D inspections:

- a. End-point electrical parameters shall be specified in Table 1.
- b. Steady-state life test, Method 1005 of Mil-Std-883:
 1. Test condition A, B, C, D.
 2. TA = +125°C, minimum.
 3. Test duration, 1000 hours, except as permitted by Method 1005 of Mil-Std-883.

TABLE 2. ELECTRICAL TEST REQUIREMENTS

| Mil-Std-883 Test Requirements | Subgroups per Method 5005, Table 1 |
|--|------------------------------------|
| Interim Electric Parameters Method 5004 | 1 |
| Final Electrical Parameters Method 5005 | 1*, 2, 3, 9, 10, 11 |
| Group A Test Requirements Method 5005 | 1, 2, 3, 9, 10, 11 |
| Group C and D End-Point Electrical Parameters Method 5005 | 1 |

* PDA applies to Subgroup 1 only.